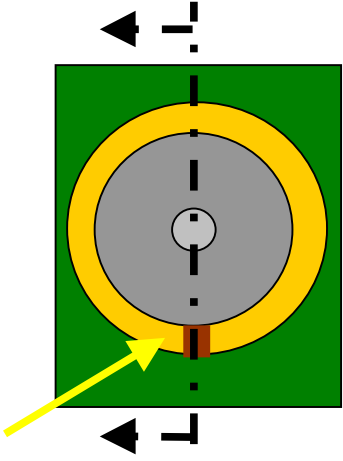


EROSION OF COPPER TRACKS

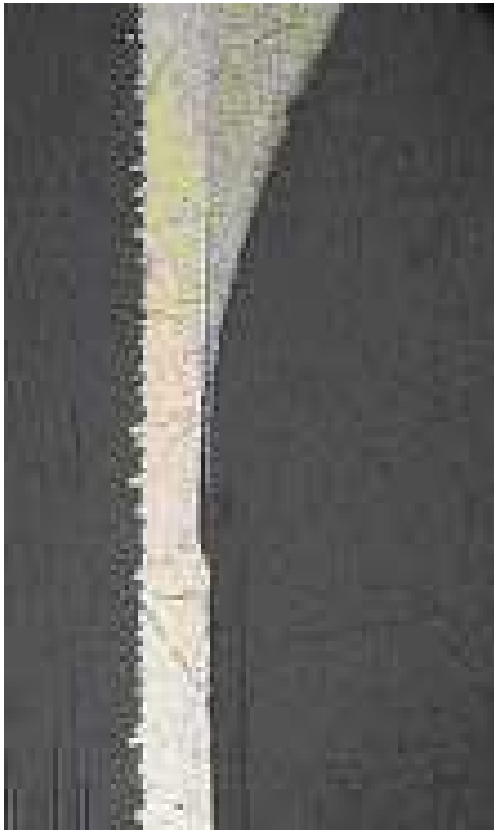


Sn-3.0Ag-0.5Cu

Sn-0.7Cu+Ni

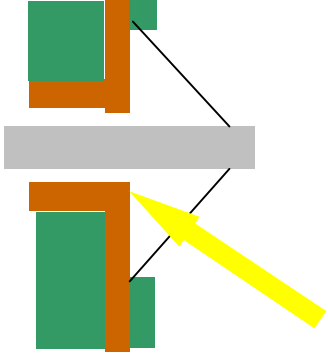


250° C 0.8m/min 3.3sec

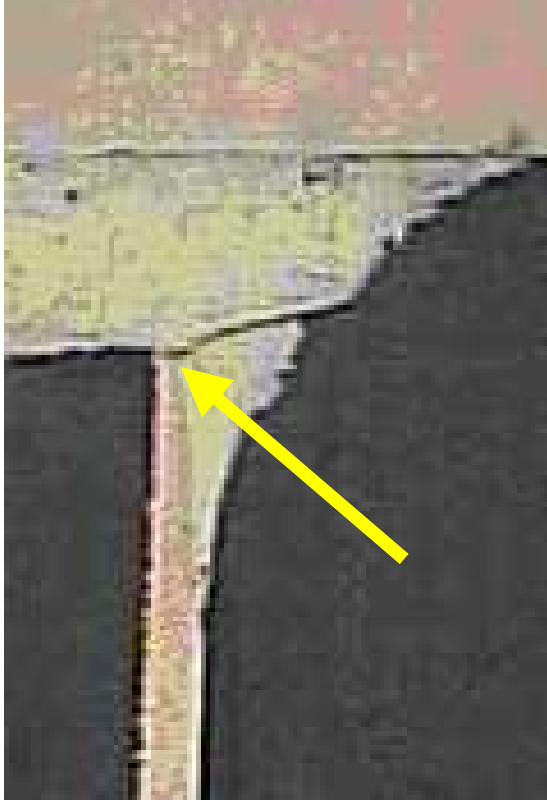


255° C 0.8m/min 4.0sec

EROSION OF COPPER TRACKS



Sn-3.0Ag-0.5Cu



250°C 0.8m/min 3.3sec

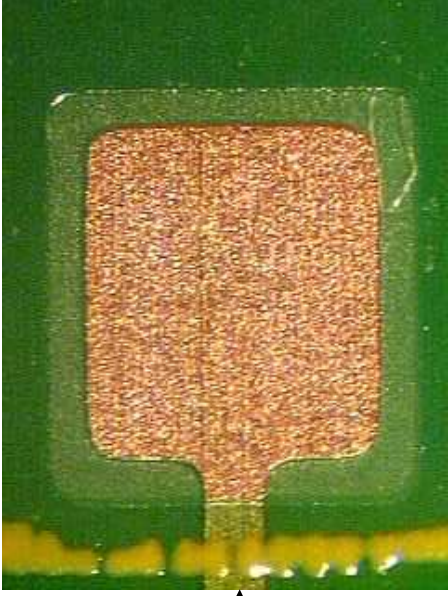
Sn-0.7Cu+Ni



255°C 0.8m/min 4.0sec

LEACHING OF COPPER PAD

Original Pad
18 μ m Copper



After 6 Passes over Wave Soldering Machine
105 $^{\circ}$ C Preheat, 256 $^{\circ}$ C Solder Temperature, 4 seconds contact time



Sn-37Pb



Sn-3.0Ag-0.5Cu



SN100C

LEACHING OF COPPER PAD



Original Pad
18 μ m Copper

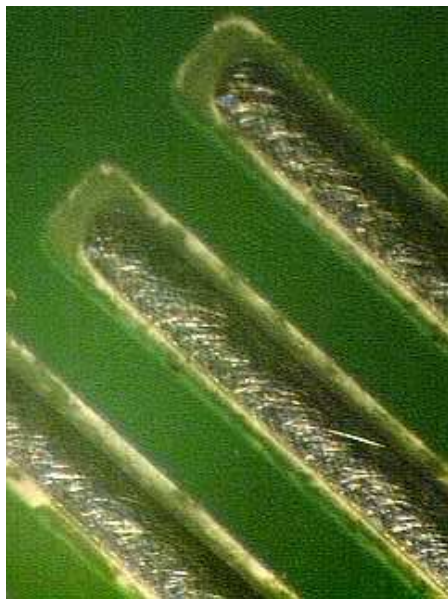
After 6 Passes over Wave Soldering Machine
105 $^{\circ}$ C Preheat, 256 $^{\circ}$ C Solder Temperature, 4 seconds contact time



Sn-37Pb



Sn-3.0Ag-0.5Cu

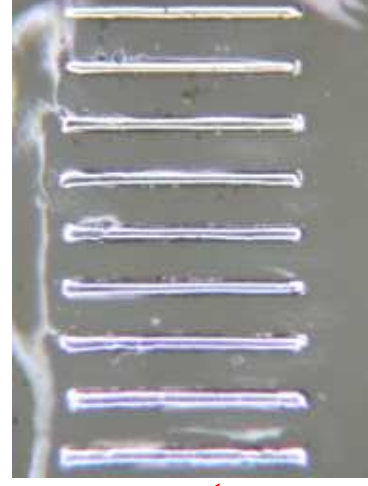
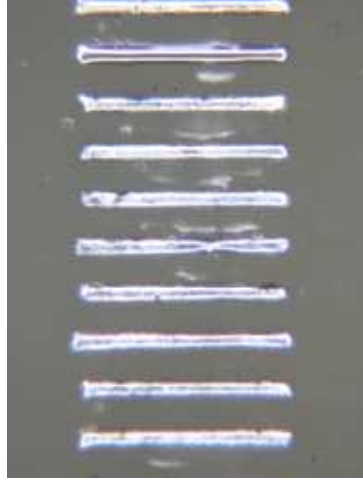
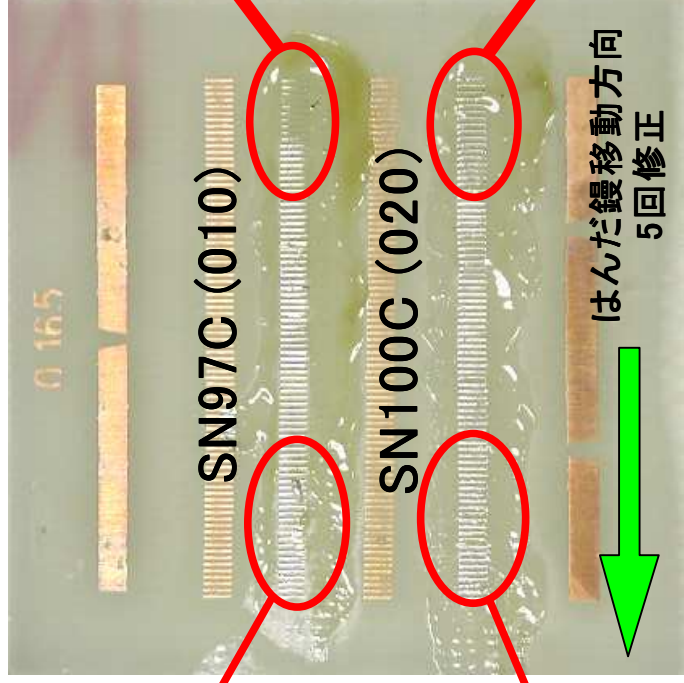
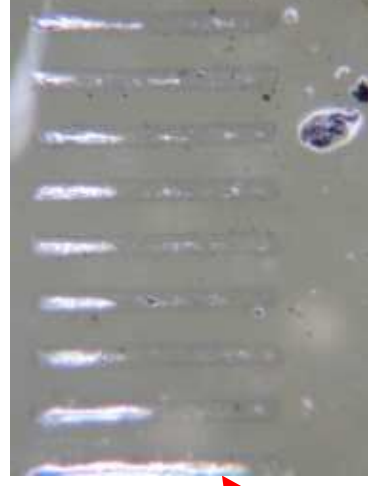
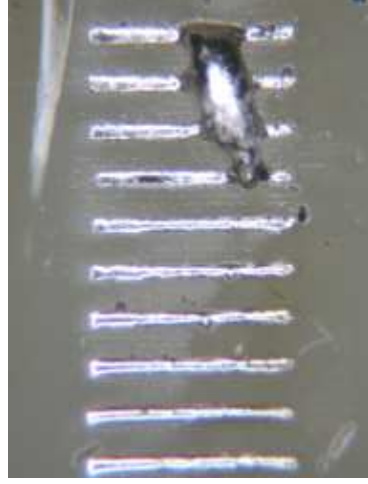


SN100C

はんだの切れと銅箔食われ

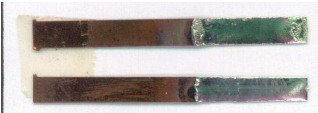



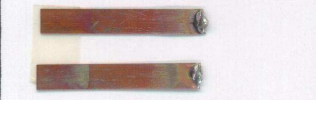




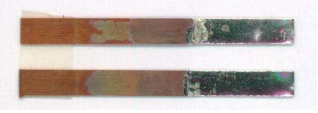
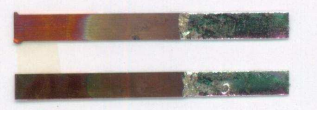
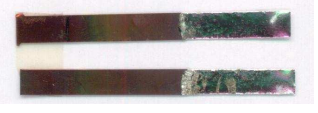





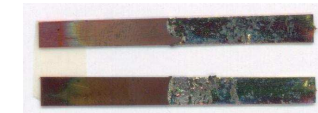

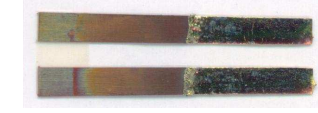

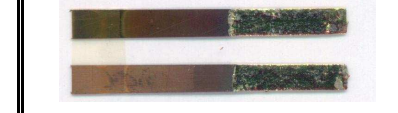


はんだの切れ

銅箔食われ



基板の説明
銅箔厚み : 16ミクロン
ランド幅 : 0.165mm
ランド間隔 : 0.165mm

こて先温度 : 350°C

		IMMERSION TIME (MINUTES)								
		1	1.5	2	3	5	8	10	20	
Sn- 0.7Cu+ Ni										
	Sn- 3Cu+Ni									
		Sn- 4Cu+Ni								

**Sn-
0.7Cu+
Ni**

**Sn-
3Cu+Ni**

**Sn-
4Cu+Ni**